NSN 5962-01-337-8568

Memory Microcircuit - Page 1 of 1



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Body Length:
Between 0.442 inches and 0.458 inches
Body Width:
Between 0.442 inches and 0.458 inches
Body Height:
Between 0.064 inches and 0.100 inches
Maximum Power Dissipation Rating:
413.0 milliwatts
Operating Tempurature Range:
-55.0/+125.0 degrees celsius
Storage Tempurature Range:
-65.0/+150.0 degrees celsius
Features Provided:
Hermetically sealed and burn in and programmable and high performance
Inclosure Material:
Ceramic
Inclosure Configuration:
Leadless flat pack
Output Logic Form:
Complementary-metal oxide-semiconductor logic
Input Circuit Pattern:
14 input
Terminal Surface Treatment:
Solder
Voltage Rating And Type Per Characteristic:
-0.5 volts power source and 7.0 volts power source
Time Rating Per Chacteristic:
50.00 nanoseconds propagation delay time, low to high level output and 50.00 nanoseconds propagation delay time, high to low level
output
Memory Device Type:
Prom
Test Data Document:
96906-mil-std-883 standard (includes industry or association standards, individual manufactureer standards, etc.).
Terminal Type And Quantity:
28 leadless
Shelf Life:
N/a
Unit Of Measure:
Demilitarization:

Fiig:

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Yes - demil/mli